

FIG. 1

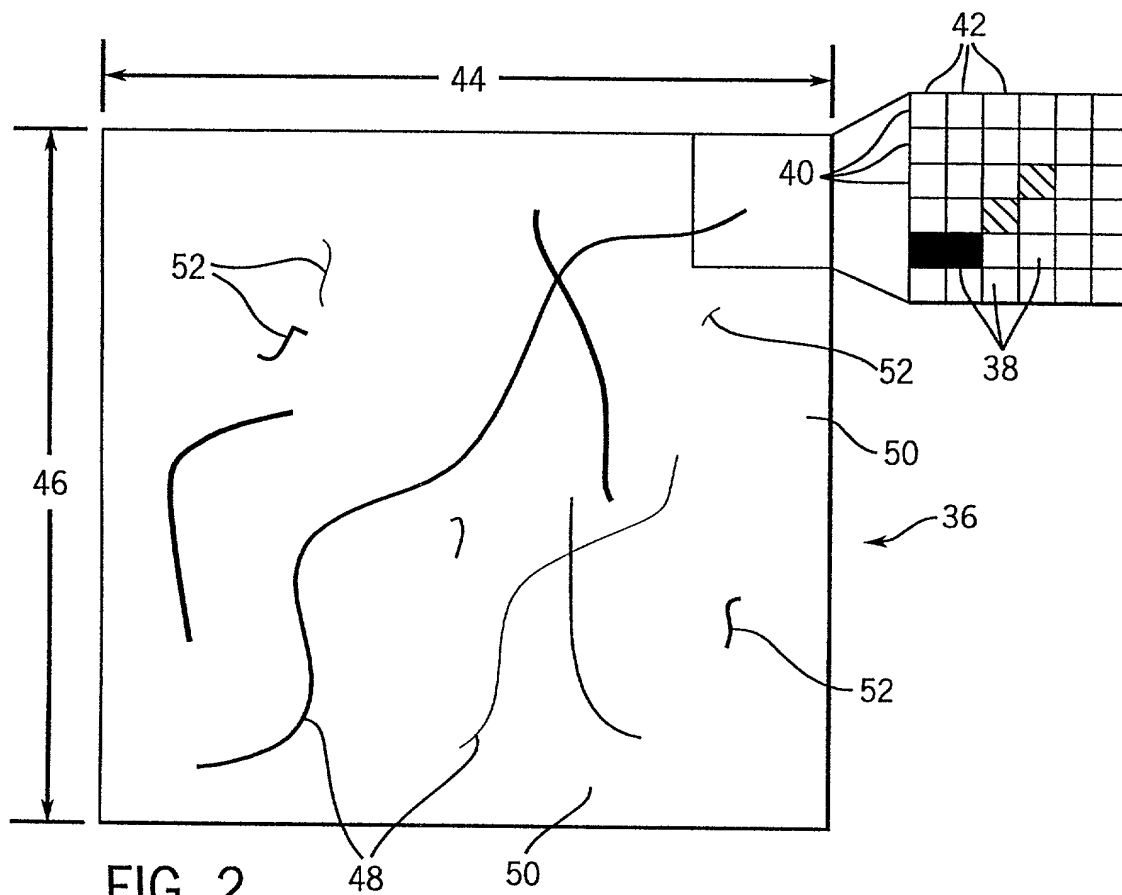


FIG. 2

FIG. 3

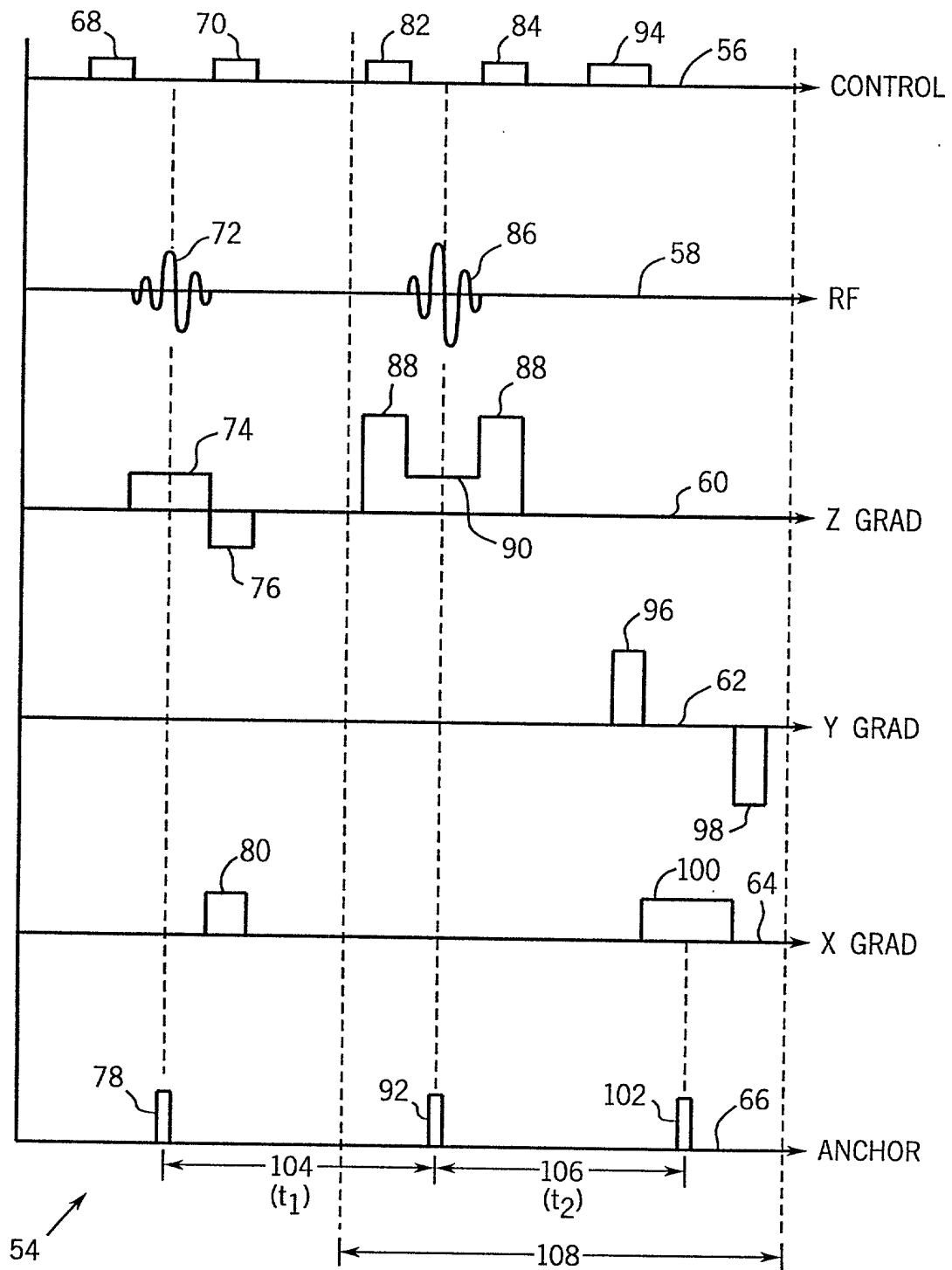


FIG. 4

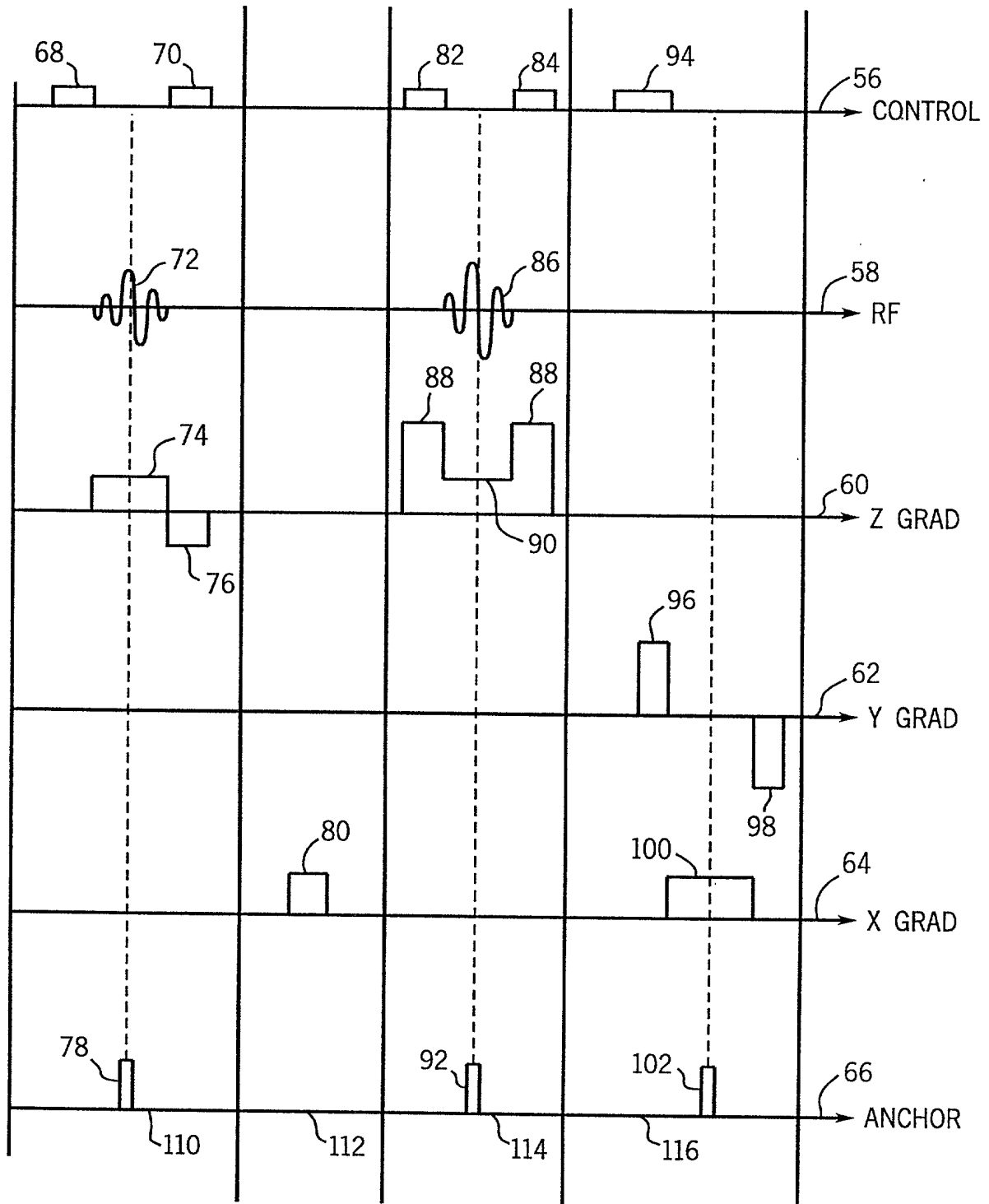


FIG. 5

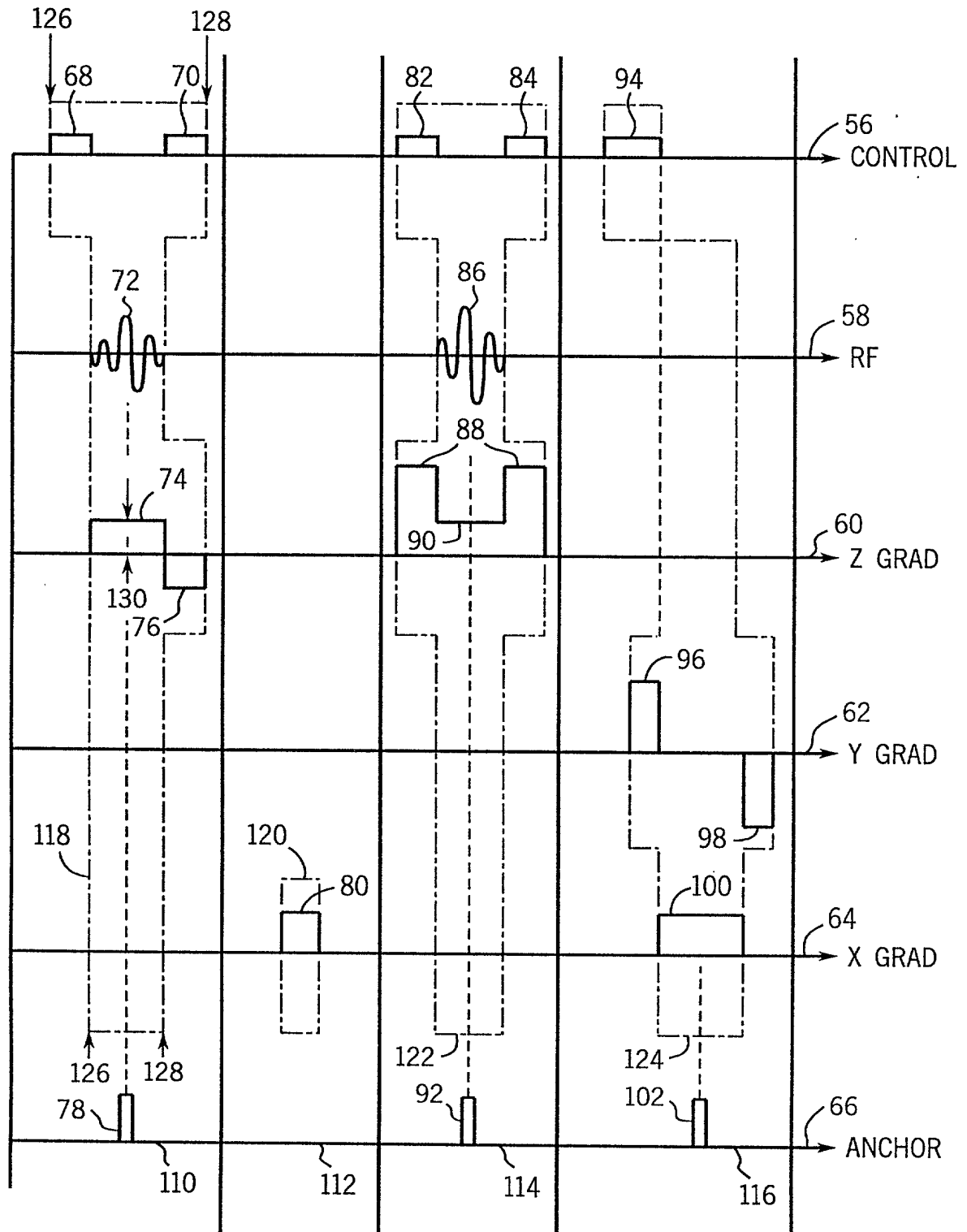
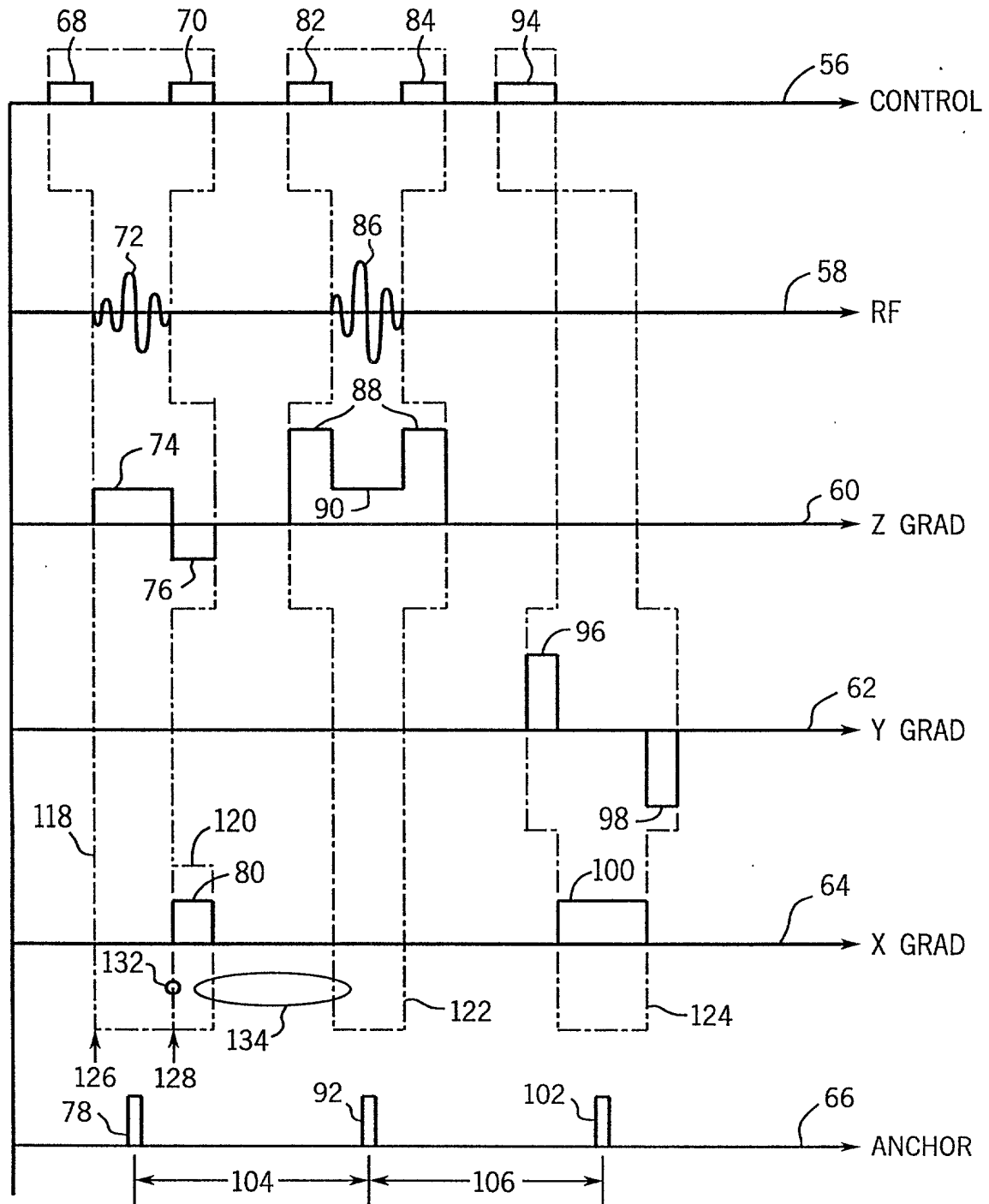


FIG. 6



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FIG. 7

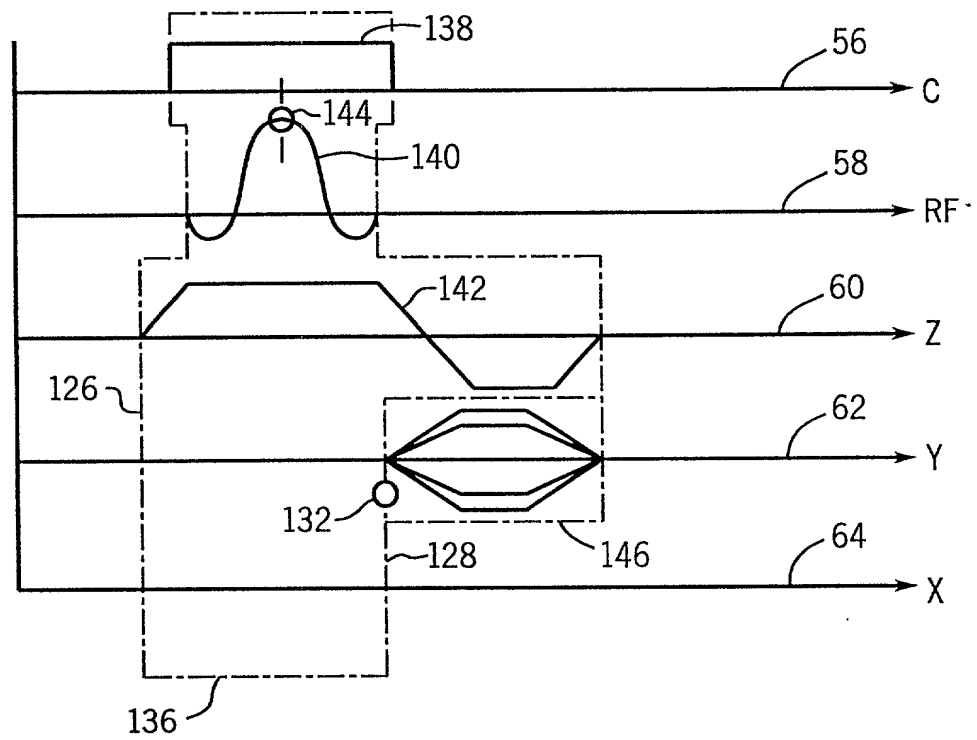
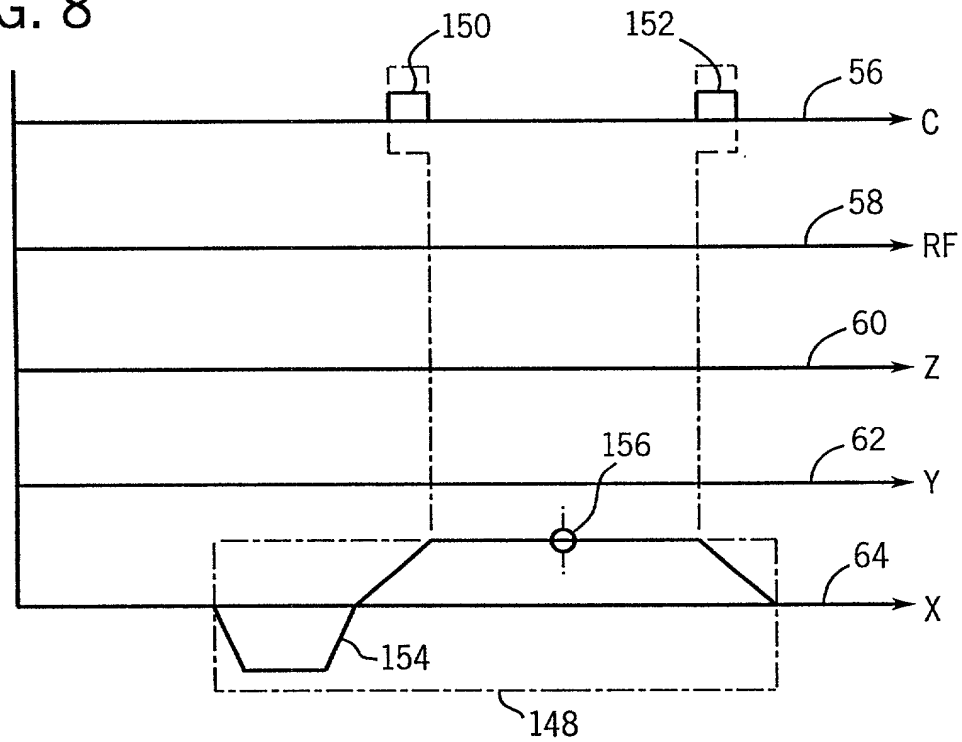


FIG. 8



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FIG. 10 is a schematic diagram of a multi-layered structure, likely a semiconductor device or a microfluidic chip, showing various layers and features. The structure is composed of several horizontal layers, with some layers having specific features or patterns.

- Layer 56 (C):** The topmost layer, which is a thin horizontal line.
- Layer 58 (RF):** A layer below 56, featuring a wavy pattern.
- Layer 60 (Z):** A layer below 58, featuring a trapezoidal pattern.
- Layer 62 (Y):** A layer below 60, featuring a hexagonal pattern.
- Layer 64 (X):** The bottommost layer, featuring a trapezoidal pattern.

Key features and labels include:

- 138:** A rectangular feature on layer 56.
- 144:** A circular feature on layer 58.
- 140:** A wavy line on layer 58.
- 142:** A trapezoidal feature on layer 60.
- 146:** A hexagonal feature on layer 62.
- 150:** A rectangular feature on layer 56.
- 152:** A rectangular feature on layer 56.
- 154:** A trapezoidal feature on layer 64.
- 156:** A circular feature on layer 64.
- 162:** A dashed rectangular box encompassing layers 56, 58, 60, and 62.
- 136:** A dashed rectangular box encompassing layers 58, 60, and 62.
- 126:** A dashed rectangular box encompassing layers 60 and 62.
- 128:** A dashed rectangular box encompassing layer 62.
- 148:** A dashed rectangular box encompassing layers 62 and 64.